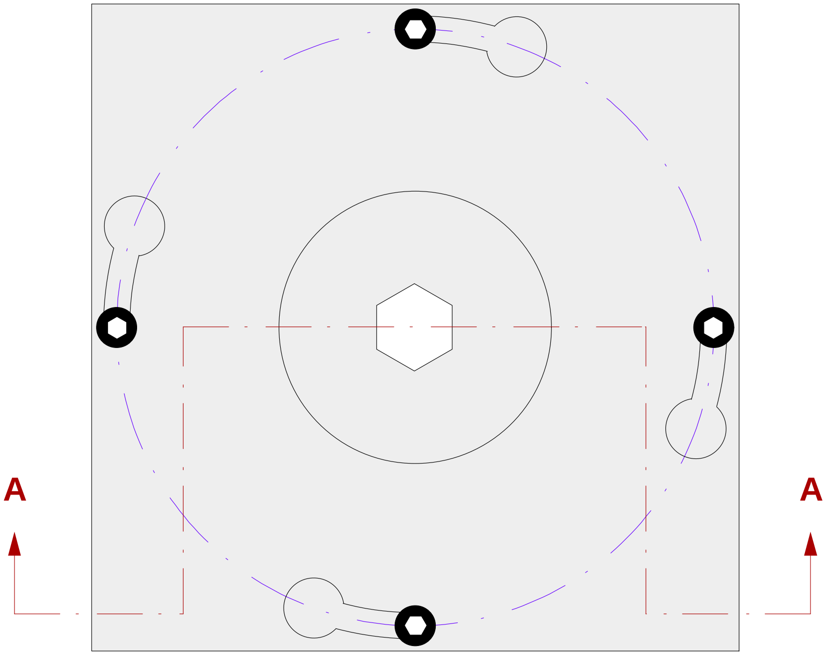
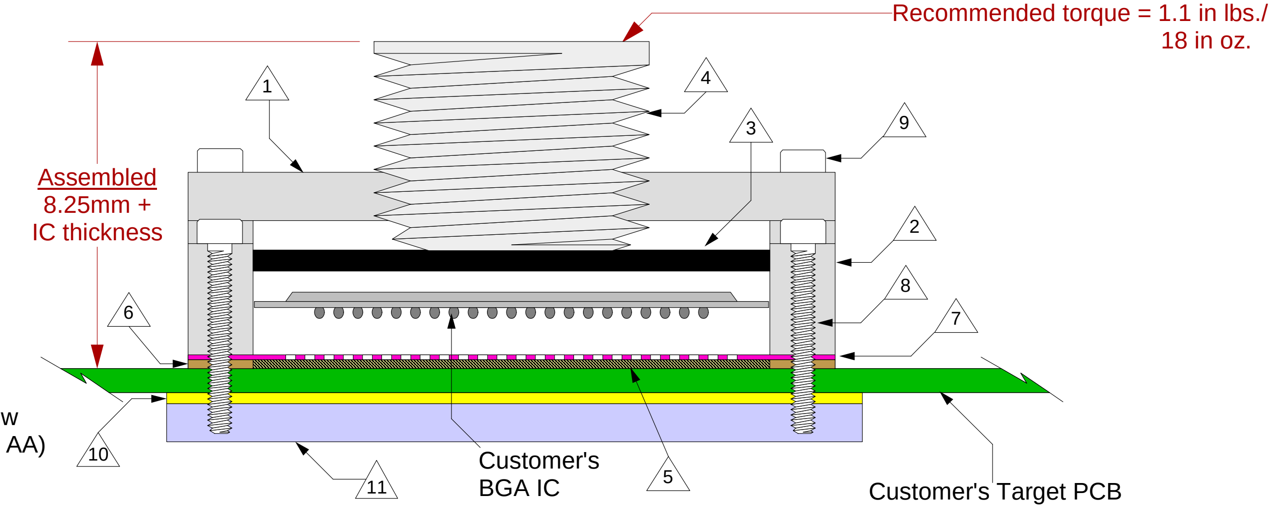
GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid



Top View



Side View
(Section AA)

1	Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
2	Socket base: Black anodized Aluminum. Thickness = 5mm.
3	Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
4	Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
5	Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
6	Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
7	Ball Guide: Kapton polyimide.
8	Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 9.525mm long.
9	Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
10	Insulation Plate: FR4/G10, Thickness = 1.59mm.
11	Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

SG-BGA-7074 Drawing	Status: Released	Scale: -	Rev: B
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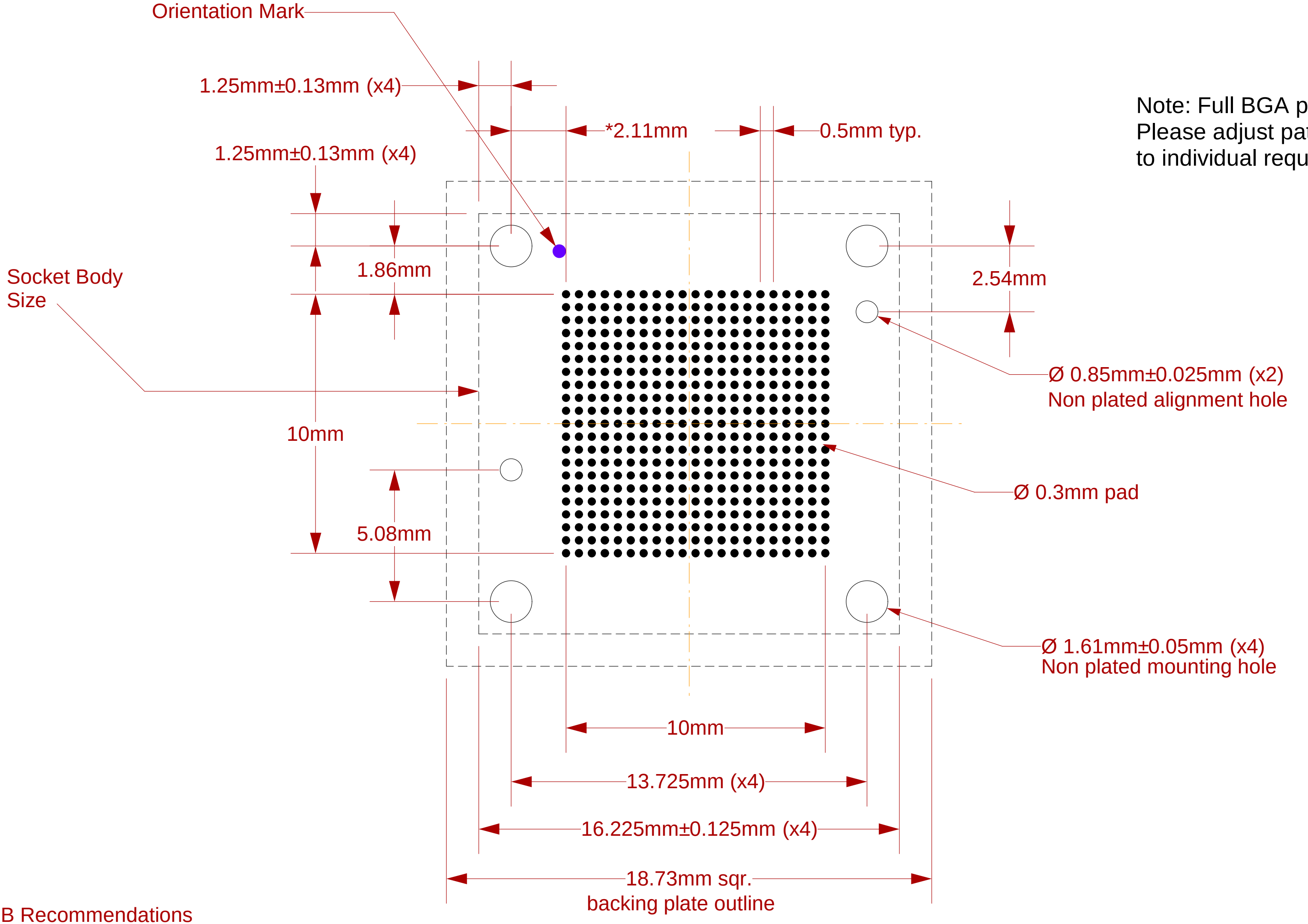
	File: SG-BGA-7074 Dwg	Modified: 7/7/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



Note: Full BGA pattern shown.
Please adjust pattern according
to individual requirements.

Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001”] unless stated otherwise.

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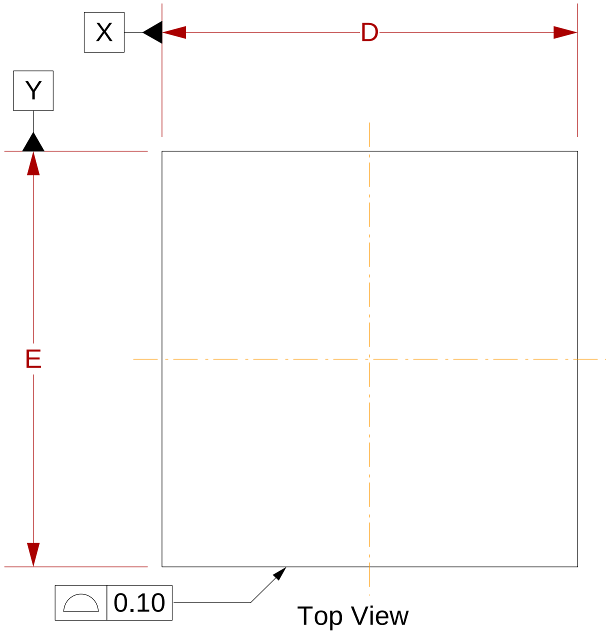
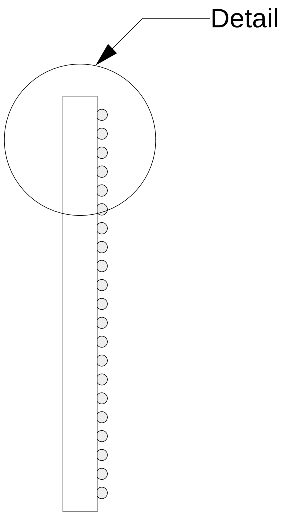
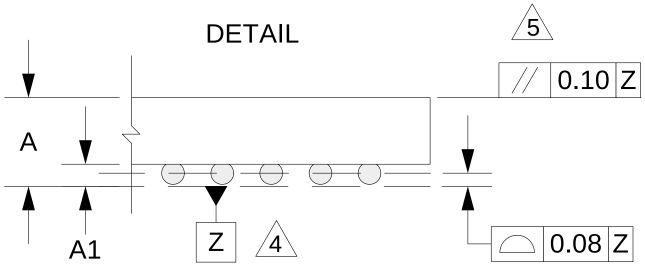
Compatible BGA Spec.

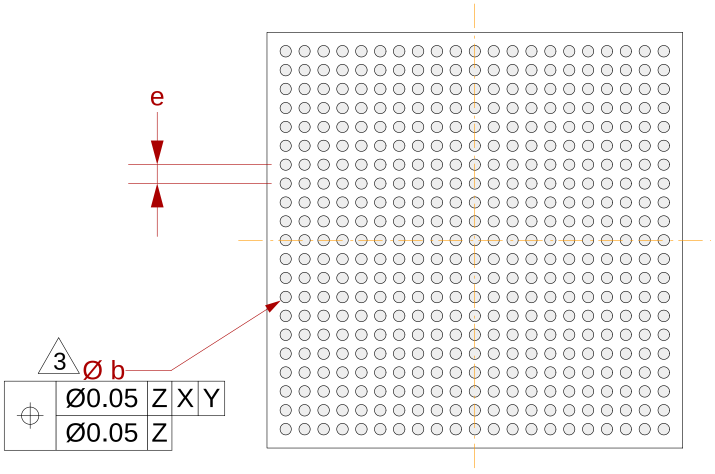


Top View



Side View





Bottom View

1. Dimensions are in millimeters.

2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.

4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.46
A1	0.17	0.27
b		0.40
D	11.0 BSC	
E	11.0 BSC	
e	0.5 BSC	

21 x 21 array

SG-BGA-7074 Drawing

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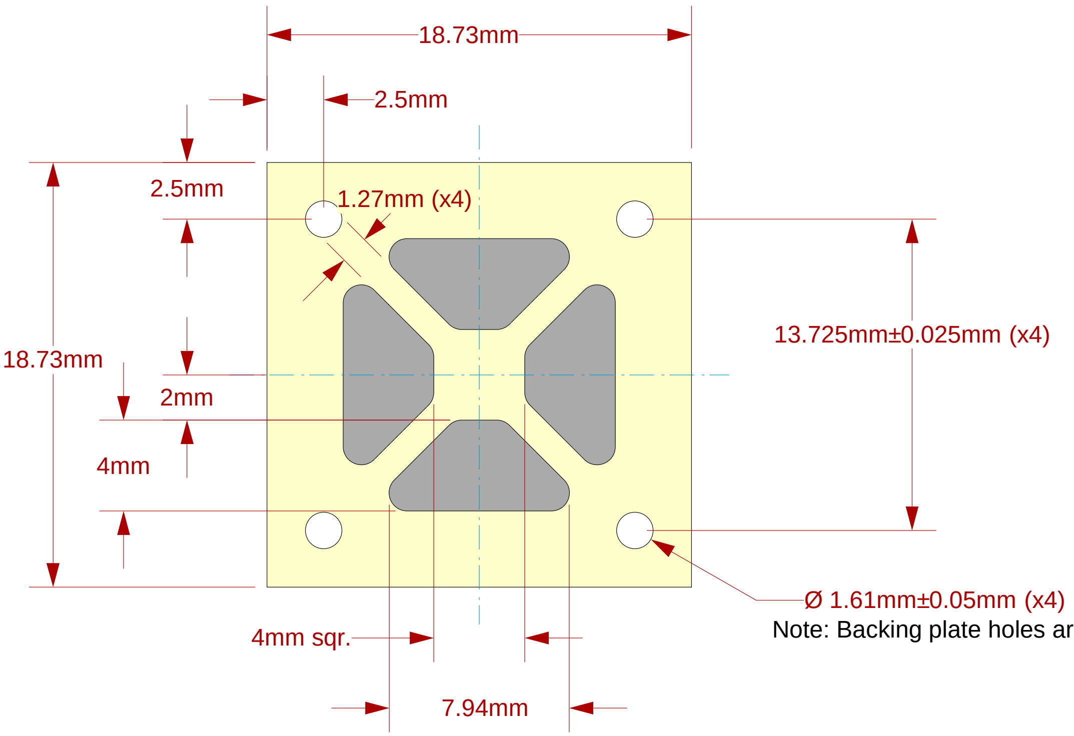
Top View



Note: Backing plate holes are tapped to accept 0-80 screws.

Side View

Description: Insulation Plate and Backing Plate

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All dimensions are in mm.
All tolerences are +/- 0.125mm.
(Unless stated otherwise)